

February 2001



FQB12N20L / FQI12N20L

200V LOGIC N-Channel MOSFET

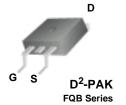
General Description

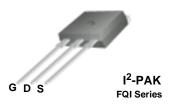
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

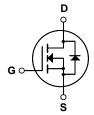
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, motor control.

Features

- 11.6A, 200V, $R_{DS(on)} = 0.28\Omega$ @ $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 16 nC)
- Low Crss (typical 17 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- Low level gate drive requirement allowing direct opration from logic drivers







Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB12N20L / FQI12N20L	Units	
V _{DSS}	Drain-Source Voltage		200	V	
I _D	Drain Current - Continuous (T _C = 25°	°C)	11.6	А	
	- Continuous (T _C = 100°C)		7.35	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	46.4	Α	
V _{GSS}	Gate-Source Voltage		± 20	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	210	mJ	
I _{AR}	Avalanche Current	(Note 1)	11.6	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	9.0	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		5.5	V/ns	
P_{D}	Power Dissipation (T _A = 25°C) *		3.5	W	
	Power Dissipation (T _C = 25°C)		90	W	
	- Derate above 25°C		0.72	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.39	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to	25°C		0.14		V/°C
I _{DSS}	7 0 . 11 5 . 0	V _{DS} = 200 V, V _{GS} = 0 V				1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C				10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1.0		2.0	V
R _{DS(on)}	Static Drain-Source	$V_{GS} = 10 \text{ V}, I_D = 5.8 \text{ A}$ $V_{GS} = 5 \text{ V}, I_D = 5.8 \text{ A}$			0.22	0.28	
DO(OII)	On-Resistance				0.25	0.32	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 30 \text{ V}, I_{D} = 5.8 \text{ A}$ (N	Note 4)		12.7		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			120 17	1080 155 22	pF pF pF
	'				17	22	p⊦
	ing Characteristics	T					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 100 \text{ V}, I_{D} = 11.6 \text{ A},$			15	40	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$			190	390	ns
t _{d(off)}	Turn-Off Delay Time	(No	ote 4, 5)		60	130	ns
t _f	Turn-Off Fall Time				120	250	ns
Q _g	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_D = 11.6 \text{ A},$			16	21	nC
Q _{gs}	Gate-Source Charge Gate-Drain Charge	$V_{GS} = 5 \text{ V}$	ote 4, 5)		2.8 7.6		nC nC
Q _{gd}	Gate-Diam Charge	,			7.0		IIC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings					
I _S	Maximum Continuous Drain-Source Diode Forward Current					11.6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current					46.4	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 11.6 \text{ A}$				1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 11.6 A,			128		ns
Q _{rr}	Reverse Recovery Charge	$dl_{\rm F}$ / $dt = 100 A/\mu s$	Note 4)		0.56		μС

- $\label{eq:Notes:Notes:Notes:1} \begin{tabular}{ll} Notes: & 1. Repetitive Rating: Pulse width limited by maximum junction temperature $2. L=2.3mH, $I_{AS}=11.6A, $V_{DD}=50V, $R_{G}=25.\Omega$, Starting $T_{J}=25^{\circ}C$ $3. $I_{SD}\leq 11.6A, $di/dt\leq 300A/\mu_{S}, V_{DD}\leq BV_{DSS}, Starting $T_{J}=25^{\circ}C$ $4. Pulse Test: Pulse width $\leq 300\mu_{S}, Duty cycle $\leq 2\%$ $5. Essentially independent of operating temperature 4.000×10^{-10} $$

Typical Characteristics

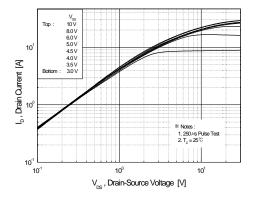


Figure 1. On-Region Characteristics

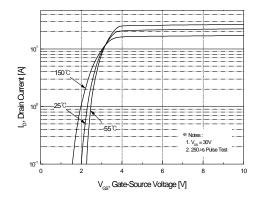


Figure 2. Transfer Characteristics

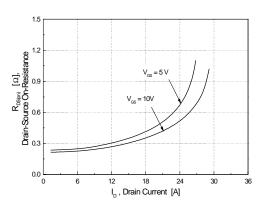


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

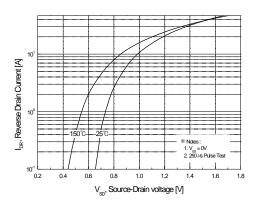


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

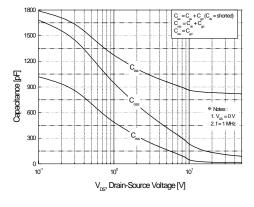


Figure 5. Capacitance Characteristics

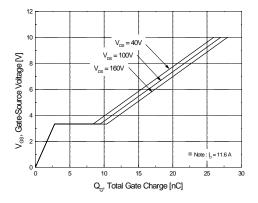
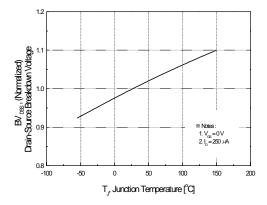


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



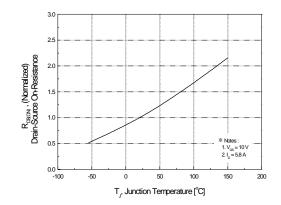
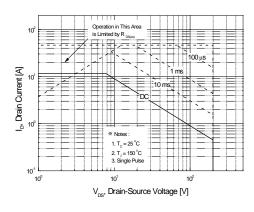


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



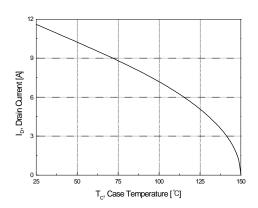


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

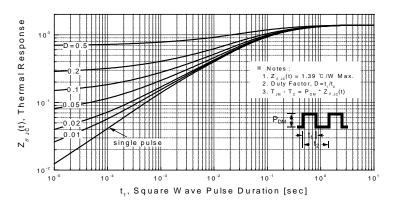
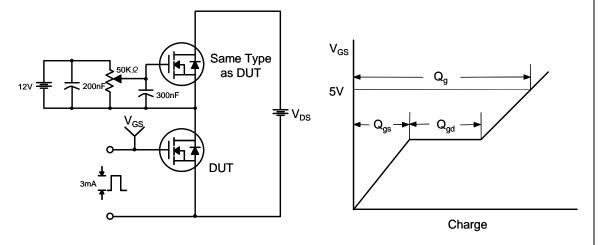


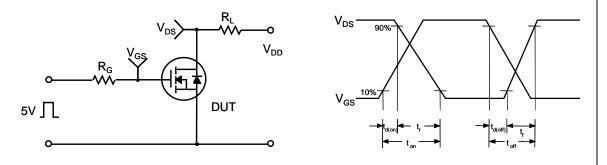
Figure 11. Transient Thermal Response Curve

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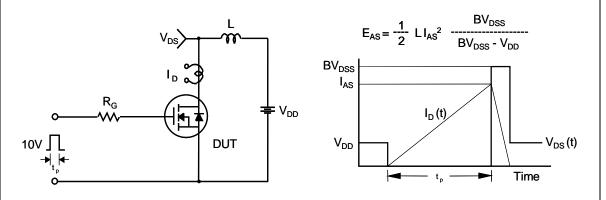
Gate Charge Test Circuit & Waveform



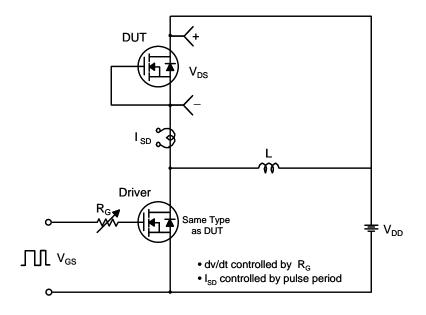
Resistive Switching Test Circuit & Waveforms

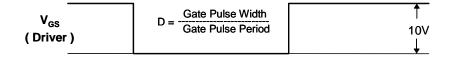


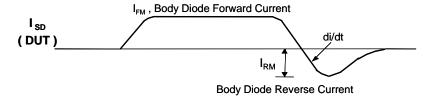
Unclamped Inductive Switching Test Circuit & Waveforms

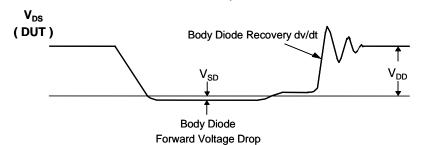


Peak Diode Recovery dv/dt Test Circuit & Waveforms

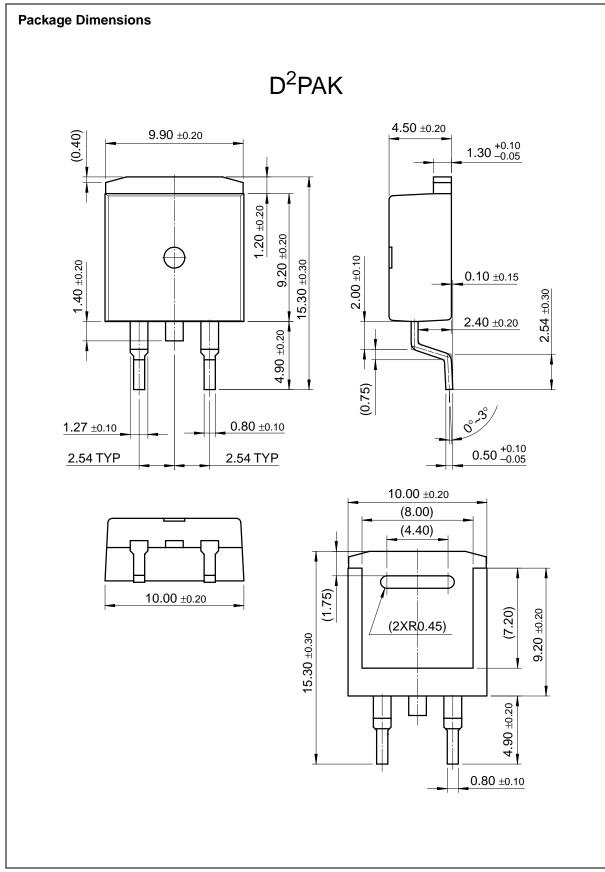


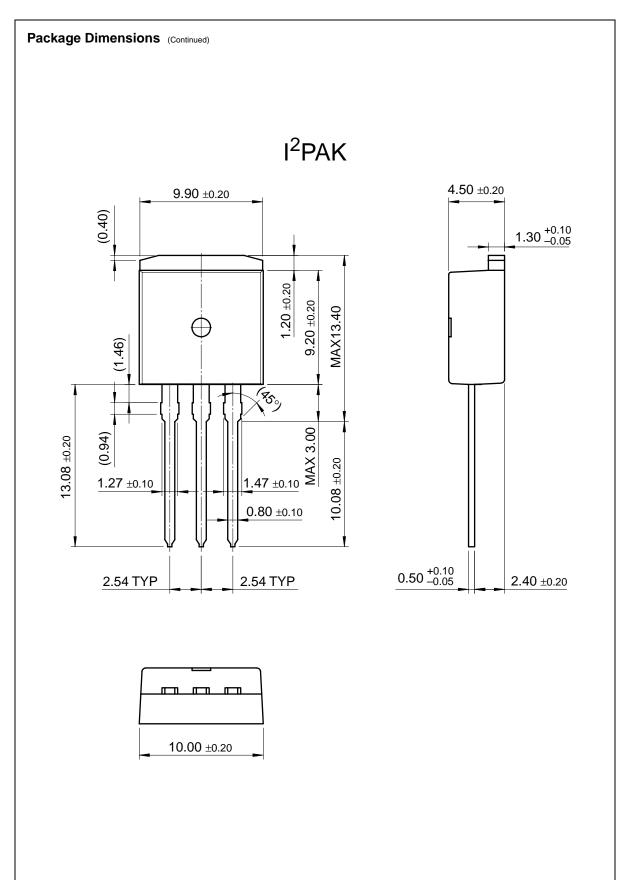






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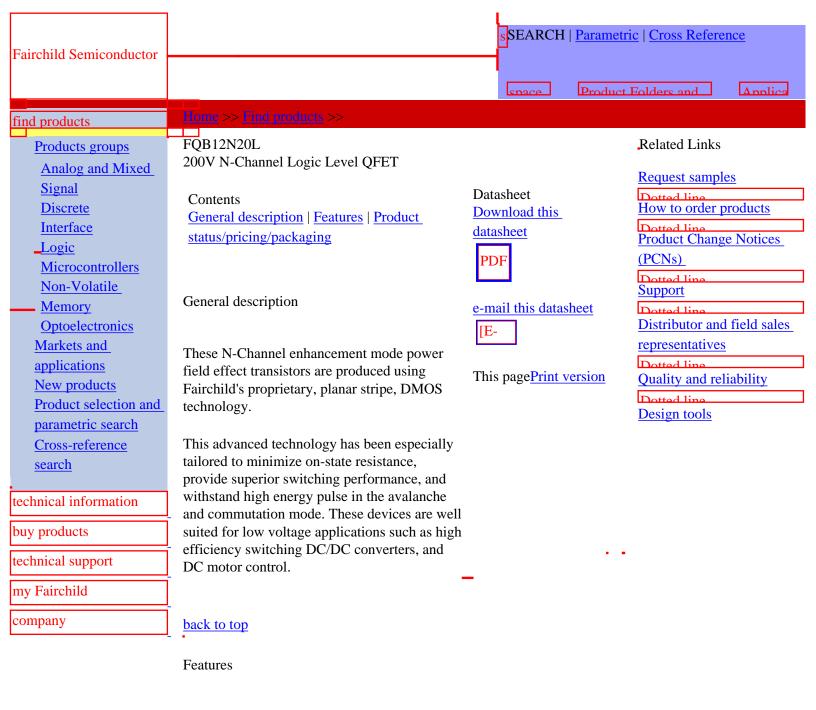
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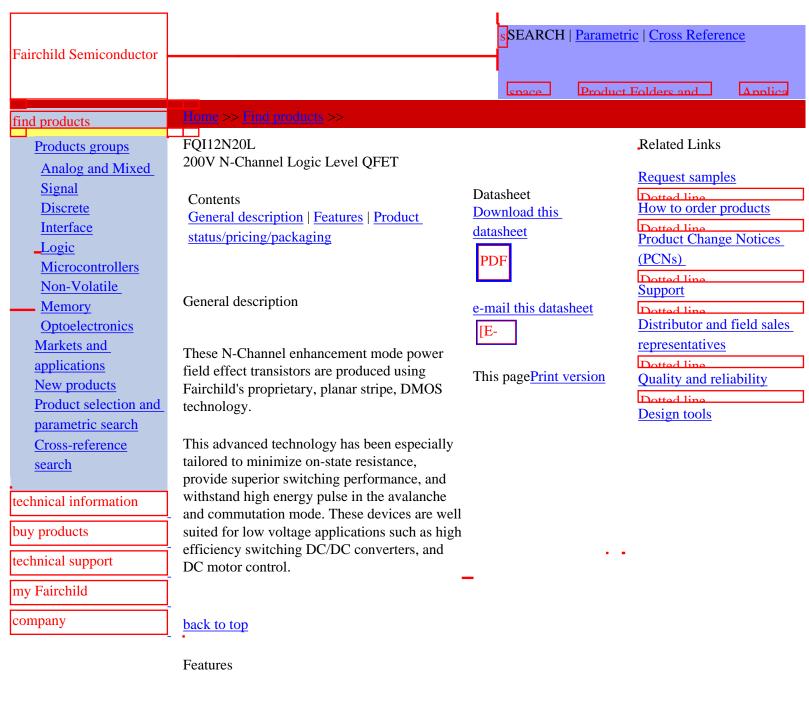
Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB12N20LTM	Full Production	\$0.69	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
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